SDAS006B – APRIL 1982 – REVISED DECEMBER 1994

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

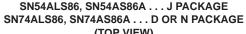
These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean functions $Y = A \oplus B$ or $Y = \overline{AB} + \overline{AB}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

The SN54ALS86 and SN54AS86A are characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS86 and SN74AS86A are characterized for operation from 0°C to 70°C.

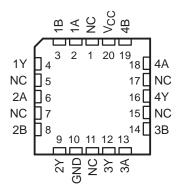
FUNCTION TABLE (each gate)											
INP	UTS	OUTPUT									
Α	В	Y									
L	L	L									
L	Н	н									
н	L	н									
н	Н	L									

logic symbol[†]

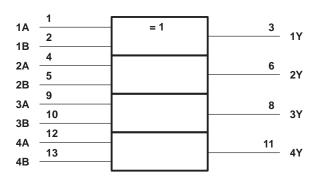


	(10		
1A 1B 1Y 2A 2B 2Y GND	1 2 3 4 5 6	, 14 13	V _{CC} 4B 4A 4Y 3B 3A 3Y
			I

SN54ALS86, SN54AS86A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



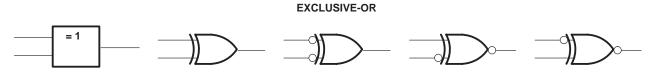
POST OFFICE BOX 655303

DALLAS, TEXAS 75265
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HOUSTON, TEXAS 77251-1443

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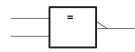
exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



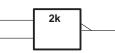
These are five equivalent exclusive-OR symbols valid for an 'ALS86 or 'AS86A gate in positive logic. Negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



The output is active (low) if all inputs are at the same logic level (i.e., A = B).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Operating free-air temperature range, T _A : SN54ALS86	-55°C to 125°C
SN74ALS86	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS86 SN74ALS86			6			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-0.4			-0.4	mA
IOL	Low-level output current			4			8	mA
ТА	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				154ALS8	36	SN	6		
PARAMETER	TEST C	ONDITIONS	MIN	typ‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	l _l = –18 mA			-1.5			-1.5	V
VOH	$V_{CC} = 4.5 V$ to 5.5 V,	I _{OH} = -0.4 mA	V _{CC} –2			V _{CC} -2	2		V
Mar	V_{OL} $V_{CC} = 4.5 V$	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
VOL		I _{OL} = 8 mA					0.35	0.5	V
l	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
Ιн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
١ _{١L}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
۱ _O §	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	V _{CC} = 5.5 V,	All inputs at 4.5 V		3.9	5.9		3.9	5.9	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VC CL RL TA	V,	UNIT			
		, , , , , , , , , , , , , , , , , , ,	SN54A	LS86	SN74ALS86			
			MIN	MAX	MIN	MAX		
^t PLH	A or B	V	3	22	3	17		
^t PHL	(other input low)	Y		14	2	12	ns	
^t PLH	A or B	V	3	22	3	17	20	
tPHL	(other input high)	ľ	2	12	2	10	ns	

 \P For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} Input voltage, V _I		
Operating free-air temperature range, T_A :		
	SN74AS86A	 0°C to 70°C
Storage temperature range		 –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	154AS86	A	SN74AS86A			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-2			-2	mA
IOL	Low-level output current			20			20	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				154AS86	Α	SN	174AS86	A	UNIT
PARAMETER	TEST	CONDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	I _I = -18 mA			-1.2			-1.2	V
VOH	V _{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
VOL	$V_{CC} = 4.5 V,$	I _{OL} = 20 mA		0.35	0.5		0.35	0.5	V
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
IIН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١ _{١L}	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-0.5			-0.5	mA
۱ ₀ §	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-30		-112	-30		-112	mA
Іссн	$V_{CC} = 5.5 V,$	$V_{I(A)} = 4.5 V, V_{I(B)} = 0$		11	18		11	18	mA
ICCL	V _{CC} = 5.5 V,	V _I = 4.5 V		20	38		20	38	mA

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

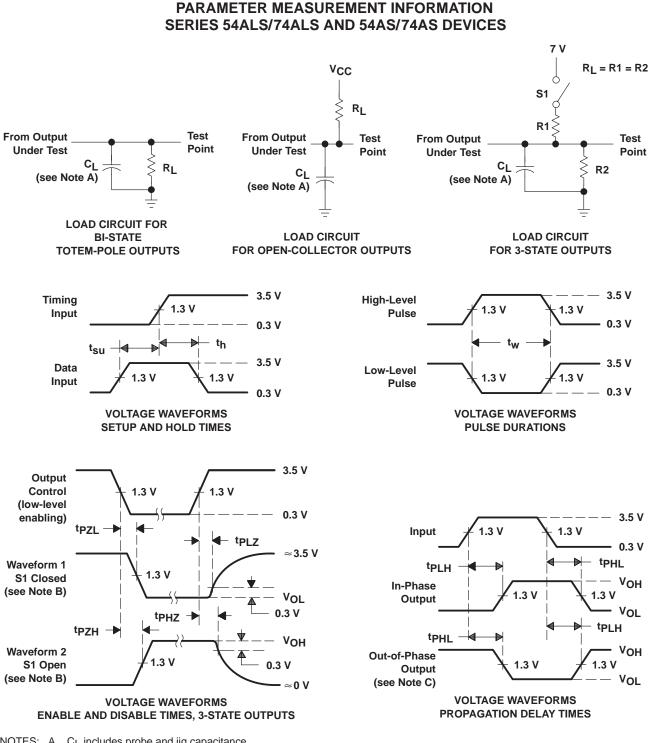
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VC CL RL TA	UNIT			
			SN54A	S86A	SN74AS86A		
			MIN	MAX	MIN	MAX	
^t PLH	A or B	×		8.5	2	7.5	
^t PHL	(other input low)	Y	2	8	2	6.5	ns
^t PLH	A or B	×	1	8	1	6.5	
^t PHL	(other input high)	T	1	9	1	7	ns

 \P For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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15-Oct-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-88621012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8862101CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-8862101DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
5962-9757201Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9757201QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54ALS86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN74ALS86D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS86DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS86DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS86DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS86DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS86DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS86N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS86N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74ALS86NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS86NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS86NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS86NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS86AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS86ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS86ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS86ADRE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI
SN74AS86ADRG4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI
SN74AS86AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS86ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54ALS86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54ALS86W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54AS86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS86AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
				-				

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⁽¹⁾ The marketing status values are defined as follows:

RUMENTS

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

OBSOLETE: It has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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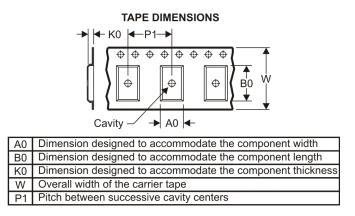
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS86NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

29-Jul-2009



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS86DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74ALS86NSR	SO	NS	14	2000	346.0	346.0	33.0

MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

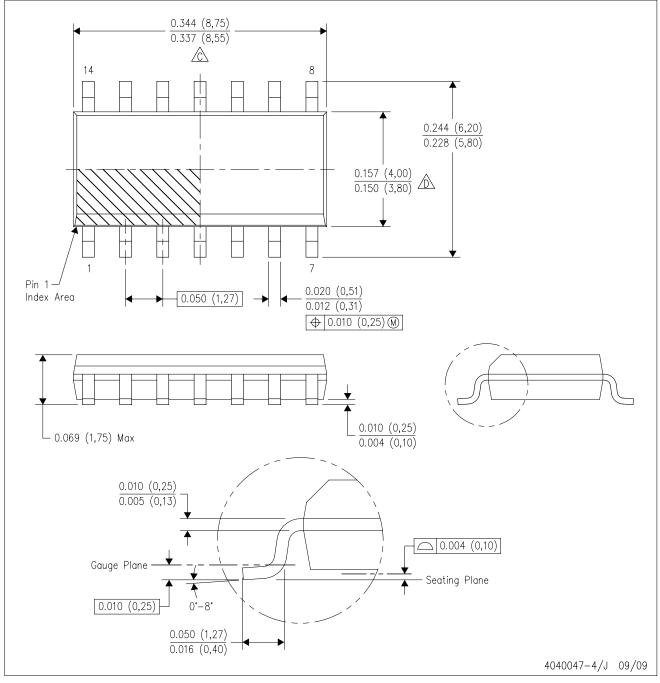
14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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RF/IF and ZigBee® Solutions	www.ti.com/lprf	Wireless	www.ti.com/wireless

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